

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## MS2A40LDF

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Product specification

## FEATURES



- Low Forward Voltage Drop
- Extremely Small DFN1610-2L Package
- Surface Device Type Mounting
- RoHS Compliant
- Green EMC
- Band Indicates Cathode
- Tape and reel: 3,000Pcs/ 7" reel

## APPLICATIONS

- Low voltage rectification
- Reverse polarity protection
- Low power consumption applications

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## Reference News

PACKAGE OUTLINE	Marking
	
DFN1610-2L	

**MAXIMUM RATING (Ta=25°C unless otherwise noted)**

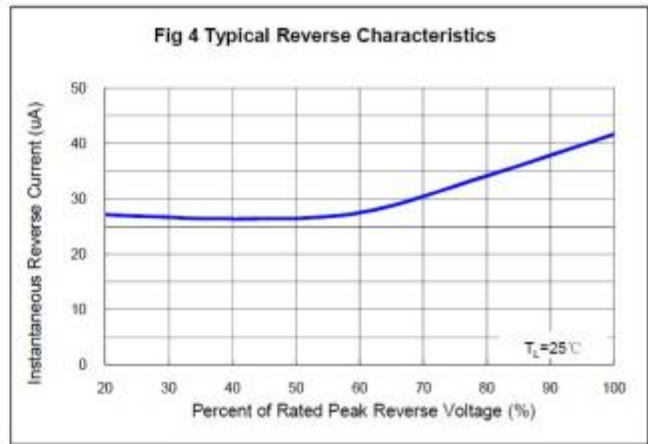
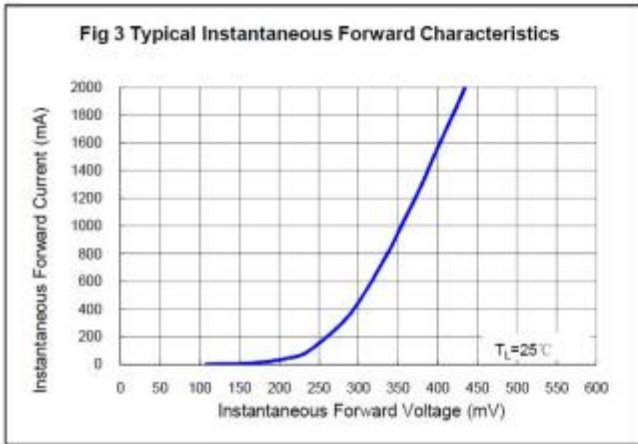
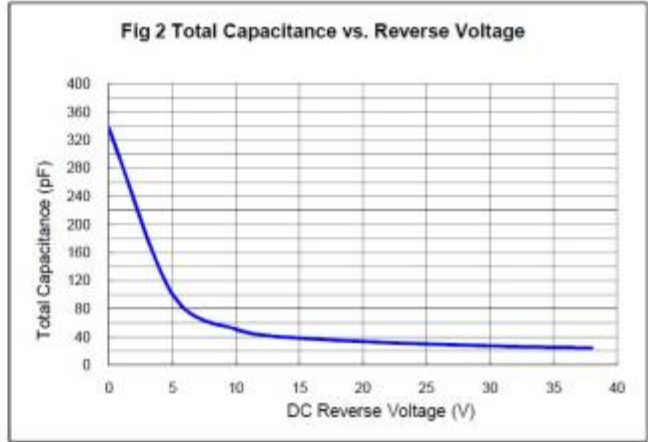
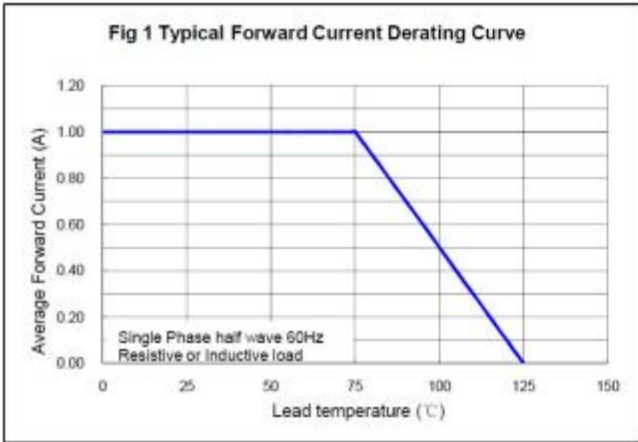
Symbol	Parameter	Value	Units
VRRM	Maximum repetitive reverse voltage	40	V
VR	Maximum DC blocking reverse voltage	40	V
IF(AV)	Average Forward Current	2	A
IFSM	Peak Forward Surge Current (At 8.3ms single half sine-wave)	20	A
TJ	Operating Junction Temperature	-50 to +125	°C
TSTG	Storage Temperature Range	-50 to +150	°C

These ratings are limiting values above which the serviceability of the diode may be impaired.

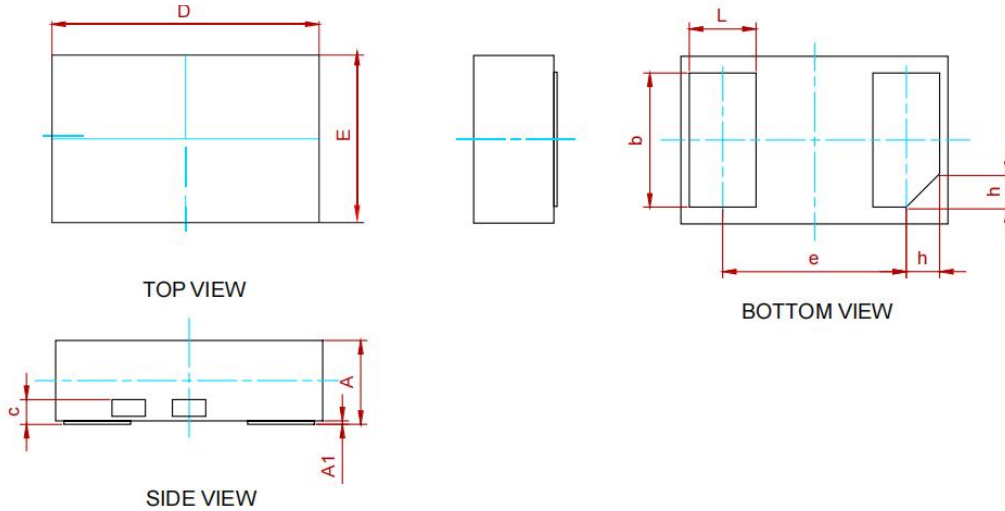
**ELECTRICAL CHARACTERISTICS (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Breakdown Voltage at IR=0.1mA	VBR	40			V
Reverse Leakage Current at VR=40V	IR			80	μA
Forward Voltage at IF=1A	VF		0.37	0.42	V
Forward Voltage at IF=2A	VF			0.50	V
Junction Capacitance VR = 0V, f = 1MHz	CJ		340	400	pF

**ELECTRICAL CHARACTERISTICS CURVE**

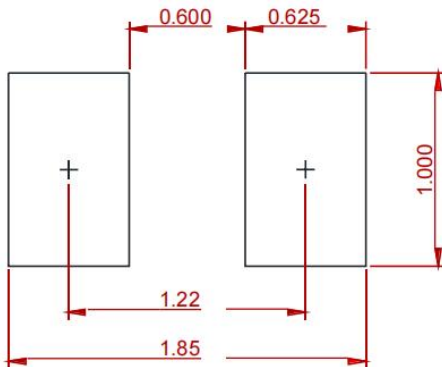


**PACKAGE MCHANICAL DATA**



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.45	0.50	0.55
A1	0.00	0.02	0.05
c	0.15 Ref.		
b	0.75	0.80	0.85
L	0.35	0.40	0.45
D	1.55	1.60	1.65
E	0.95	1.00	1.05
e	1.10 BSC		
h	0.20 Ref.		

**Suggested Pad Layout**



**Notes:**

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

**REEL SPECIFICATION**

P/N	PKG	QTY
MS2A40LDF	DFN1610-2	3000

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